

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03	100.0	0.41
<b>Subtotal</b>				<b>0.03</b>	<b>100</b>	<b>0.41</b>
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.06	100.0	1
<b>Subtotal</b>				<b>0.06</b>	<b>100</b>	<b>1</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.09	100.0	1.41
<b>Subtotal</b>				<b>0.09</b>	<b>100</b>	<b>1.41</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.04	0.23
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.58
	Copper alloy	Copper (Cu)	7440-50-8	36.85	99.86	584.18
<b>Subtotal</b>				<b>36.9</b>	<b>100</b>	<b>584.99</b>
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.84	3.0	29.13
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.67	6.0	58.26
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	6.12	10.0	97.1
	Carbon Black	Carbon black	1333-86-4	0.31	0.5	4.86
	Filler	Misc. Silica compounds (generic)	14808-60-7	47.77	78.0	757.38
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.53	2.5	24.27
<b>Subtotal</b>				<b>61.24</b>	<b>100</b>	<b>971</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	0.63	100.0	10
<b>Subtotal</b>				<b>0.63</b>	<b>100</b>	<b>10</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.05	5.0	0.83
	Lead alloy	Silver (Ag)	7440-22-4	0.03	2.5	0.42
	Lead alloy	Lead (Pb)	7439-92-1	0.97	92.5	15.42
<b>Subtotal</b>				<b>1.05</b>	<b>100</b>	<b>16.67</b>
<b>Total</b>				<b>100</b>	<b>100</b>	<b>1585.48</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.